

NtRAM Code Information(1/2)

Last Updated : November 2008

K 7 X X X X X X X X - X X X X X X X

1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18

1. Memory (K)

2. Sync(NtRAM) SRAM : 7

3. Small Classification

M : Sync Burst + NtRAM

N : Sync Pipelined Burst + NtRAM

4~5. Density

40 : 4M 80 : 8M 16 : 16M

32 : 32M 64 : 64M

6~7. Organization

18 : x18 36 : x36

8~9. Vcc, Interface, Mode

01 : 3.3V, LVTTL, 2E2D WIDE

09 : 3.3V, LVTTL, Hi SPEED

25 : 3.3V, LVTTL, SB-FT WIDE

31 : 2.5/ 3.3V, LVTTL, 2E2D

35 : 2.5/ 3.3V, LVTTL, SB-FT

45 : 2.5V, LVTTL, 2E2D

49 : 2.5V, LVTTL, Hi SPEED

10. Generation

M : 1st Generation

A : 2nd Generation

B : 3rd Generation

11. "—"

12. Package

E : FBGA (Lead-Free)

F : FBGA

P : (L)QFP (Lead-Free)

Q : (L)QFP

C : CHIP BIZ

W : WAFER

13. Temp, Power

- COMMON (Temp, Power)

C : Commercial, Normal

I : Industrial, Normal

- WAFER, CHIP BIZ Level Division

0 : NONE, NONE

1 : Hot DC sort

2 : Hot DC, selected AC sort

14~15. Speed

- Sync Burst + NtRAM

65 : 6.5ns

75 : 7.5ns

- Other Small Classification (Clock Cycle Time)

11 : 117MHz

13 : 133MHz

16 : 166MHz

20 : 200MHz

25 : 250MHz

NtRAM Code Information(2/2)

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16. Packing Type

- Common to all products, except of Mask ROM
- Divided into TAPE & REEL(In Mask ROM, divided into TRAY, AMMO Packing Separately)

Divide	Packing Type	New Marking
Component	TAPE & REEL	T
	Other (Tray, Tube, Jar)	0 (Number)
	Stack	S
Component (Mask ROM)	TRAY	Y
	AMMO PACKING	A
Module	MODULE TAPE & REEL	P
	MODULE Other Packing	M

17~18. Customer "Customer List Reference"